

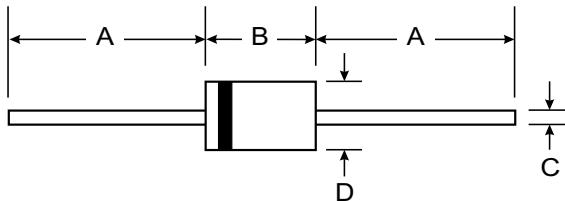
VOLTAGE RANGE: 90 - 100V
CURRENT: 2.0 A

Features

- Schottky Barrier Chip
- Guard Ring Die Construction for Transient Protection
- High Current Capability
- Low Power Loss, High Efficiency
- High Surge Current Capability
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Applications

Mechanical Data

- Case: DO-15, Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Weight: 0.40 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



DO-15		
Dim	Min	Max
A	25.40	—
B	5.50	7.62
C	0.686	0.889
D	2.60	3.60

All Dimensions in mm

Maximum Ratings and Electrical Characteristics (T_A = 25°C unless otherwise specified)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbol	SB2H90	SB2H100	Unit
Maximum repetitive peak reverse voltage	V _{RRM}	90	100	V
Working Peak Reverse Voltage	V _{RWM}	90	100	V
Maximum DC blocking voltage	V _{DC}	90	100	V
Maximum average forward rectified current at T _A = 25°C	I _{F(AV)}	2.0		A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	75		A
Peak repetitive reverse surge current at t _p = 2.0μs, 1KHz	I _{RRM}	1.0		A
Critical rate of rise of reverse voltage	dV/dt	10,000		V/μs
Typical thermal resistance ⁽²⁾	R _{θJA} R _{θJL}	45 14		°C/W
Storage temperature range	T _{STG}	-55 to +175		°C
Maximum operating junction temperature	T _J	+175		°C

Electrical Characteristics (T_A = 25°C unless otherwise noted)

Max. instantaneous forward voltage ⁽¹⁾	I _F = 2A, T _J = 25°C I _F = 2A, T _J = 125°C	V _F	0.79 0.65	V
Maximum DC reverse current at rated DC blocking voltage	T _J = 25°C T _J = 125°C	I _R	10 4	μA mA

Notes: (1) Pulse test: 300μs pulse width, 1% duty cycle

(2) P.C.B. mounted with 0.2 x 0.2" (5.0 x 5.0mm) copper pad areas

Ratings and Characteristic Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig. 1 – Forward Current Derating Curve

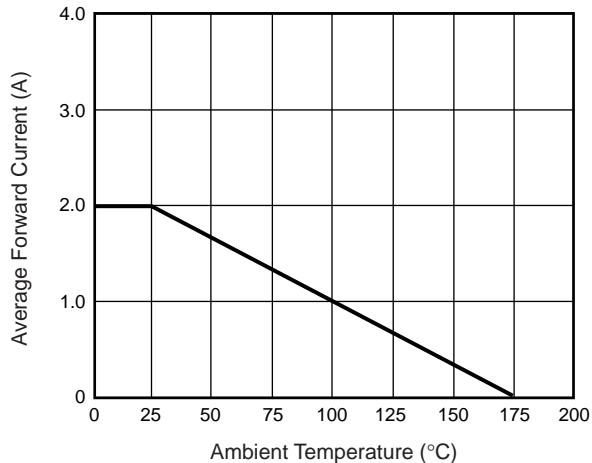


Fig. 2 – Typical Instantaneous Forward Characteristics

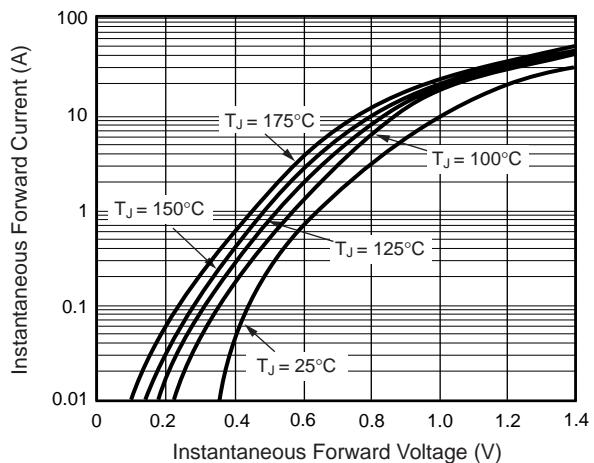


Fig. 3 – Typical Reverse Characteristics

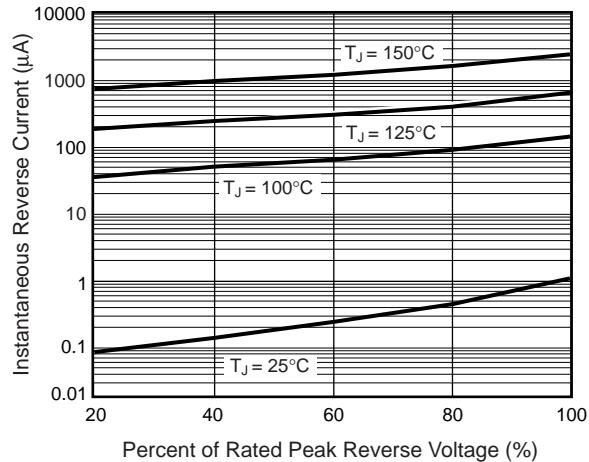


Fig. 4 – Typical Junction Capacitance

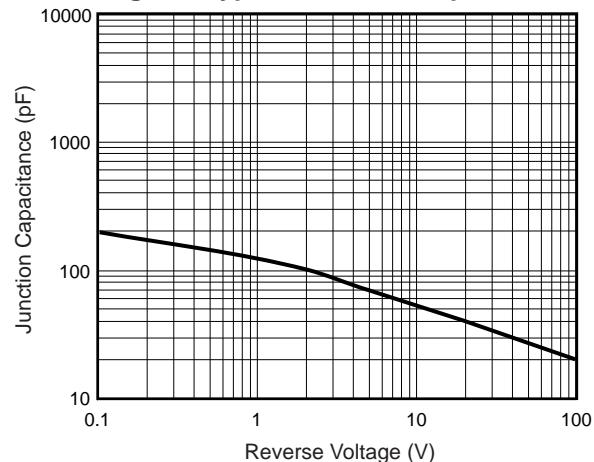


Fig. 5 - Typical Transient Thermal Impedance

